



Final Product Change Notification

201909006F01

Issue Date: 25-Sep-2019

Effective Date: 23-Dec-2019

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



QUALITY

Change Category

Wafer Fab Process

Wafer Fab Materials

Wafer Fab Location

Firmware

Assem by Process

Product Marking

Test Location

Assem by Materials

Mechanical Specification

Test Process Errata

Assem by Location

Packing/Shipping/Labelling

Test Equipment Electrical spec./Test coverage

Other

i.MX6SLL/RT1020/RT1050/RT1015/RT1060/RT1064 FAB Site Transfer from SMIC8 to SMICB2

Description of Change

NXP Semiconductors announces the Wafer Fabrication site transfer for i.MX6SLL/RT1020/RT1050/RT1015/RT1060/RT1064 from the current SMIC8, Shanghai, China Wafer Fabrication site to the SMICB2, Beijing, China Wafer Fabrication site.

Wafer Fabrication site transfer was successfully qualified adhering to NXP specifications.

Reason for Change

SMIC8 wafer Fabrication site will cease production for 40nm technology and therefore, NXP is moving production of i.MX6SLL/RT1020/RT1050/RT1015/RT1060/RT1064 to internal SMICB2 Wafer Fabrication site.

Qualification of SMICB2 Wafer Fabrication site is required for customer supply assurance.

Identification of Affected Products

There is no change to orderable part number. NXP will have traceability by ECID

Product Availability

Sample Information

Samples are available from 04-Oct-2019

Please refer to the attachment about the sample part numbers that will be made available.

Production

Planned first shipment 01-Jan-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality. Equivalent wafer fabrication process currently used at SMIC8 wafer manufacturing facility will be implemented at SMICB2.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)

Additional documents: [view online](#)



Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 25-Oct-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Grace Wang

Position Product Engineer

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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